TPS3800-xx



SLVS219E - AUGUST 1999-REVISED OCTOBER 2010

ULTRA-SMALL SUPPLY VOLTAGE SUPERVISORS

Check for Samples: TPS3800-xx, TPS3801-xx, TPS3802-xx

FEATURES

- Small, 5-Pin SC-70 (SOT-323) Package
- Supply Current of 9 µA
- **Power-On Reset Generator With Fixed Delay** Time
 - TPS3800 = 100 ms
 - TPS3801 = 200 ms
 - TPS3802 = 400 ms
- Precision Supply Voltage Monitor 1.8 V, 2.5 V, 2.7 V, 3 V, 3.3 V, 5 V, and Adjustable
- Manual Reset Input (Except TPS3801-01)
- Temperature Range: -40°C to +85°C

APPLICATIONS

- Applications Using DSPs, Microcontrollers, or **Microprocessors**
- **Wireless Communication Systems**
- Portable/Battery-Powered Equipment
- **Programmable Controls**
- **Intelligent Instruments**
- **Industrial Equipment**
- **Notebook/Desktop Computers**
- **Automotive Systems**

DESCRIPTION

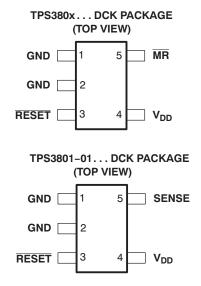
The TPS380x family of supervisory circuits monitor supply voltages to provide circuit initialization and timing supervision, primarily for DSPs and other processor-based systems.

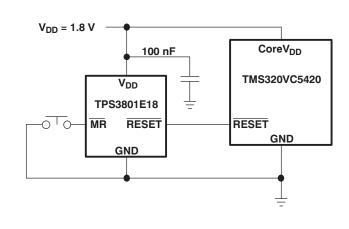
These devices assert a push-pull RESET signal when the SENSE (adjustable version) or V_{DD} (fixed version) drops below a preset threshold. The RESET output remains asserted for the factory programmed delay time after the SENSE or V_{DD} return above its threshold.

The TPS380x devices, except the TPS3801-01, incorporate a manual reset input (MR). A low level at MR causes RESET to become active.

The TPS380x uses a precision reference to achieve an overall threshold accuracy of 2%-2.5%. These devices are available in a 5-pin SC-70 package, which is only about half the size of a 5-pin SOT-23 package.

The TPS380x devices are fully specified over a temperature range of -40°C to +85°C.





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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AVAILABLE OPTIONS(1)

T _A	DEVICE NAME	THRESHOLD VOLTAGE	TYP DELAY TIME	MARKING
	TPS3801-01DCK	Adjustable ($V_{ref} = 1.14 \text{ V}$)	200 ms	ARF
	TPS3801E18DCK	1.71 V	200 ms	ARE
	TPS3801J25DCK	2.25 V	200 ms	NJA
	TPS3800G27DCK	2.5 V	95 ms	ARI
–40°C to 85°C	TPS3801L30DCK	2.64 V	200 ms	NPA
-40°C 10 85°C	TPS3801K33DCK	2.93 V	200 ms	NWA
	TPS3802L30DCK	2.64 V	380 ms	ASA
	TPS3802K33DCK	2.93 V	380 ms	ARK
	TPS3801T50DCK	4.00 V	25 ms	AVI
	TPS3801I50DCK	4.55 V	200 ms	NSA

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or refer to our web site at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1) (2)

Over operating free-air temperature range (unless otherwise noted).

	UNIT
Supply voltage, V _{DD}	7 V
SENSE	-0.3 V to 5 V
All other pins	-0.3 V to 7 V
MR	$-0.3 \text{ V to V}_{DD} + 0.3 \text{ V}$
RESET	-0.3 V to V _{DD} + 0.3 V
Maximum low-output current, I _{OL}	5 mA
Maximum high-output current, I _{OH}	–5 mA
Input-clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output-clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±20 mA
Operating junction temperature range, T _J ⁽³⁾	-40°C to +85°C
Storage temperature range, T _{stg}	−65°C to +150°C

⁽¹⁾ Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
Cumply voltage \/	TPS3801J25, TPS3801L30, TPS3801K33, TPS3801I50, TPS3801T50	2	6	V
Supply voltage, V _{DD}	All other devices	1.6	4	V
SENSE		0	See (1)	V
Input voltage, V _I		0 V _{DD} +0.3		V
High-level input voltage	ge, V _{IH}	$0.7 \times V_{DD}$	V _{DD} +0.3	V
Low-level input voltag	e, V _{IL}		$0.3 \times V_{DD}$	V
Input transition rise ar	nd fall rate at \overline{MR} , $\Delta t/\Delta V$		100	ns/V
Pull-up resistor value,	RESET	V _{Pull-up} 50μΑ		Ω
Operating free-air tem	perature range, T _A	-40	+85	°C

(1) Maximum = V_{DD} + 0.3 or 4.5 V, whichever is greater.

⁽²⁾ All voltage values are with respect to GND. For reliable operation, the device should not be operated at 7 V for more than t = 1000h continuously.

⁽³⁾ Due to the low dissipation power of this device, it is assumed that $T_J = T_A$.



ELECTRICAL CHARACTERISTICS

Over -40°C to +85°C free-air temperature range (unless otherwise noted)

PAR/	AMETER		TEST CONDITIONS		xx, TPS3801- S3802-xx	×x,				
				MIN	TYP	MAX	UNIT			
			$V_{DD} = 1.6 \text{ V to 6 V I}_{OH} = -500 \mu\text{A}$	V _{DD} -0.2						
V_{OH}	High-level output voltage	je (RESET)	$V_{DD} = 3.3 \text{ V } I_{OH} = -2 \text{ mA}$	V _{DD} -0.4			V			
			$V_{DD} = 6 \text{ V } I_{OH} = -4 \text{ mA}^{(1)}$	V _{DD} -0.4						
			$V_{DD} = 1.6 \text{ V to 6 V}, I_{OL} = 500 \mu\text{A}$			0.2				
V_{OL}	Low-level output voltag	e (RESET)	V _{DD} = 3.3 V, I _{OL} = 2 mA			0.4	V			
			$V_{DD} = 6 \text{ V}, I_{OL} = 4 \text{ mA}^{(1)}$			0.4				
	Power-up reset voltage	(2)	$V_{DD} \ge 1.1 \text{ V}, I_{OL} = 50 \mu\text{A}$			0.2	V			
		TPS380x-01		1.117	1.14	1.163				
		TPS380xE18		1.67	1.71	1.75				
	Negative-going input threshold voltage (3)	TPS380xJ25		2.2	2.25	2.3				
. ,		TPS380xG27	T 4000 to 0500	2.45	2.5	2.55				
V_{IT-}		TPS380xL30	$T_A = -40$ °C to 85°C	2.58	2.64	2.7	V			
			TPS380xK33		2.87	2.93	2.99			
		TPS380xI50		4.45	4.55	4.65				
		TPS380xT50		3.92	4	4.08				
		TPS380x-01			15					
		TPS380xx18			25					
		TPS380xx25			30					
V_{hys}	Threshold hysteresis	TPS380xx27			35		mV			
		TPS380xx30			35					
		TPS380xx33			40					
		TPS380xx50			60					
I _{IH}	High-level input current	(MR)	$\overline{MR} = 0.7 \times V_{DD}, V_{DD} = 6 \text{ V}$	-40	-60	-100				
I _{IL}	Low-level input current	(MR)	$\overline{MR} = 0 \text{ V}, \text{ V}_{DD} = 6 \text{ V}$	-130	-200	-340	μΑ			
l _l	Input current (SENSE)			-25		25	nA			
		TPS3801J25, TPS3801L30,	V _{DD} = 2 V, MR and output unconnected		9	12				
		TPS3801K33, TPS3801I50, TPS3801T50	$V_{DD} = 6 \text{ V}, \overline{\text{MR}} \text{ and output}$ unconnected		20	25				
l _{DD}	Supply current	TPS3801-01	V_{DD} = 1.6 V, SENSE = 0 V to V_{DD} , output unconnected		7	10	μА			
טטי	оцирну сынсти	1253801-01	$V_{DD} = 4 \text{ V, SENSE} = 0 \text{ V to } V_{DD},$ output unconnected		9	12				
		TPS3801E18, TPS3800G27,	V _{DD} = 1.6 V, MR and output unconnected		8	11				
		TPS3802K33, TPS3802L30	$V_{DD} = 4 \text{ V}, \overline{\text{MR}} \text{ and output}$ unconnected		13	18				
Ci	Input capacitance		$V_I = 0 V \text{ to } V_{DD}$		5		pF			

 ⁽¹⁾ Only valid for the TPS3801J25, TPS3801L30, TPS3801K33, TPS3801I50, and TPS3801T50.
 (2) The lowest supply voltage at which RESET becomes active. t_{r, VDD} ≥ 15 μs/V.
 (3) To ensure the best stability of the threshold voltage, a bypass capacitor (0.1-μF ceramic) should be placed near the supply terminals.



TIMING REQUIREMENTS

at $R_L = 1 \text{ M}\Omega$, $C_L = 50 \text{ pF}$, $T_A = +25^{\circ}\text{C}$

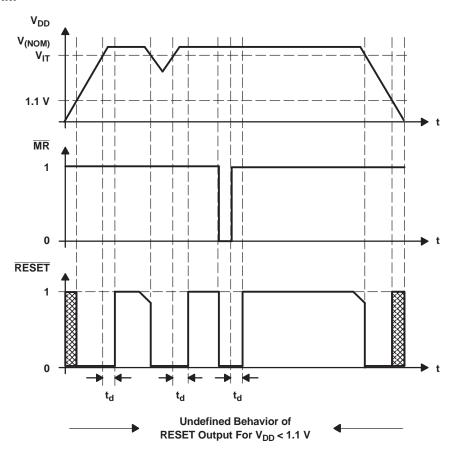
PARAMETER			TEST CONDITIONS	MIN	TYP	MAX	UNIT
	at SENSE		$V_{DD} = 1.6 \text{ V}, V_{IH} = 1.1 \times V_{IT-}, V_{IL} = 0.9 \times V_{IT-}$	1			
t _w	Pulse width	at V _{DD}	$V_{DD} = V_{IT-} + 0.2 \text{ V}, V_{DD} = V_{IT-} -0.2 \text{ V}$	3			μS
		at MR	$V_{DD} \geq V_{IT-} + 0.2 \; V, \; V_{IL} = 0.3 \times V_{DD}, \; V_{IH} = 0.7 \times V_{DD}$	100			ns

SWITCHING CHARACTERISTICS

at $R_1 = 1 \text{ M}\Omega$, $C_1 = 50 \text{ pF}$, $T_{\Delta} = +25^{\circ}\text{C}$

PARA	METER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
		TPS3801T50		15	25	35	
t _d RI	DECET and a second delay the se	TPS3800	$V_{DD} \ge V_{IT} + 0.2 \text{ V},$	60	95	140	ms
	RESET recovery delay time	TPS3801	MR ≥ 0.7 × V _{DD} See timing diagram	120	200	280	
		TPS3802		240	380	560	
t _{PHL}	Propagation (delay) time, high-to-low-level output	MR to RESET delay	$V_{DD} \ge V_{IT-} + 0.2 \text{ V},$ $V_{IL} = 0.3 \times V_{DD},$ $V_{IH} = 0.7 \times V_{DD}$		15		ns
		V _{DD} to RESET delay SENSE to RESET	$V_{IL} = V_{IT-} - 0.2 \text{ V},$ $V_{IH} = V_{IT-} + 0.2 \text{ V}$		1		μS

TIMING DIAGRAM



NOTE: $\overline{\text{RESET}}$ should not be forced high during the power-up sequence (until $V_{DD} > 1.1 \text{ V}$).



FUNCTIONAL BLOCK DIAGRAMS

FUNCTION/TRUTH TABLE. TPS380x

. 0.10 1.10 1.4/ 1.10 1.11 1.7 (BEE) 1.1 0000%										
MR	$V_{DD} > V_{IT}$	RESET								
L	0	L								
L	1	L								
н	0	L								
н	1	Н								

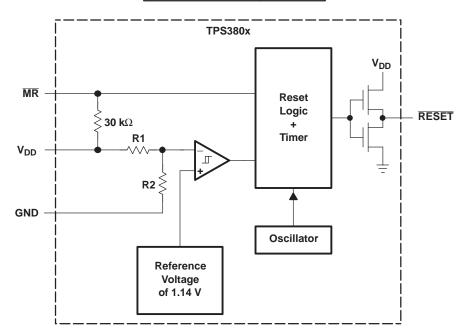


Figure 1.

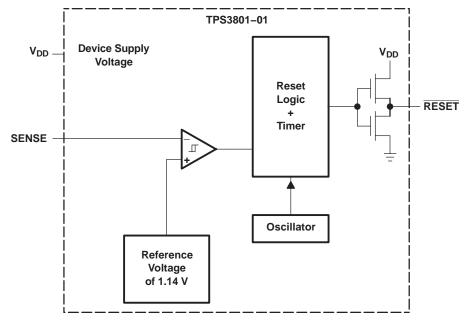
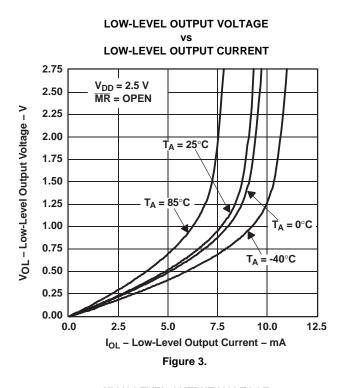
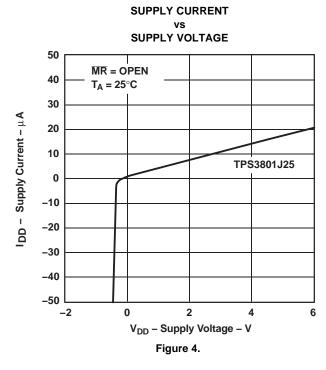


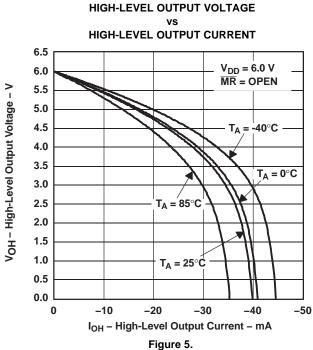
Figure 2.

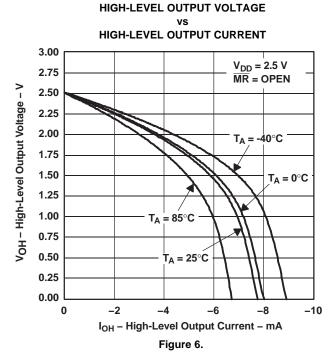


TYPICAL CHARACTERISTICS









MR = OPEN

0.6

MINIMUM PULSE DURATION AT VDD

VDD THRESHOLD OVERDRIVE VOLTAGE



TYPICAL CHARACTERISTICS (continued)

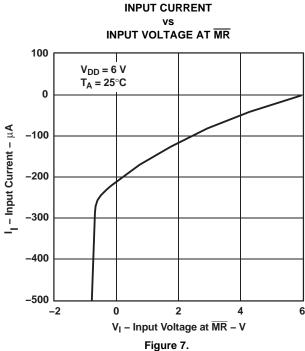
3.5

3

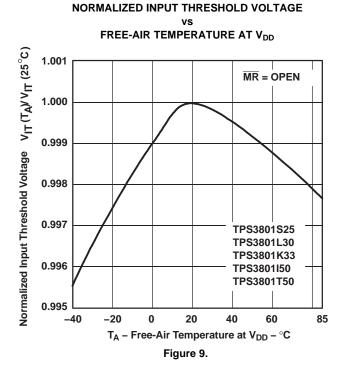
2.5

2

1.5



t_{W} – Minimum Pulse Duration at $\,V_{DD}\!-\,\mu s$ 0.5 0 0 0.2 0.4 6 V_{DD} Threshold Overdrive Voltage – V Figure 8.



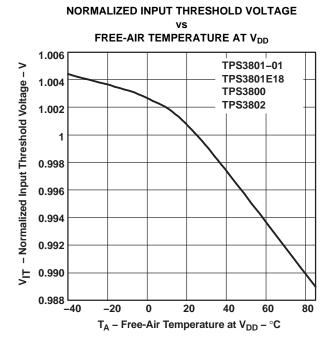
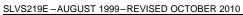


Figure 10.





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Ch	anges from Revision D (December 2006) to Revision E	Page
•	Added Pull-up resistor value, RESET to the Recommended Operating Conditions Table	2





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
TPS3800G27DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARI	Samples
TPS3800G27DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARI	Samples
TPS3801-01DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARF	Samples
TPS3801-01DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARF	Samples
TPS3801E18DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARE	Samples
TPS3801E18DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARE	Samples
TPS3801I50DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NSA	Samples
TPS3801I50DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NSA	Samples
TPS3801J25DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NJA	Samples
TPS3801J25DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NJA	Samples
TPS3801K33DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NWA	Samples
TPS3801K33DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NWA	Samples
TPS3801L30DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NPA	Samples
TPS3801L30DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	NPA	Samples
TPS3801T50DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVI	Samples
TPS3801T50DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	AVI	Samples
TPS3801T50DCKT	OBSOLET	E SC70	DCK	5		TBD	Call TI	Call TI	-40 to 85		



PACKAGE OPTION ADDENDUM

11-Apr-2013

Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
TPS3802K33DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARK	Samples
TPS3802K33DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ARK	Samples
TPS3802L30DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASA	Samples
TPS3802L30DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ASA	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

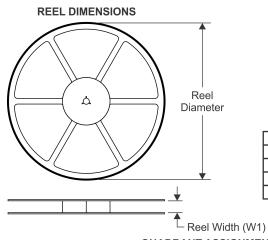
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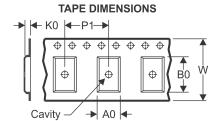
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PACKAGE MATERIALS INFORMATION

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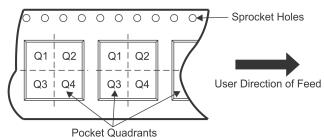
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

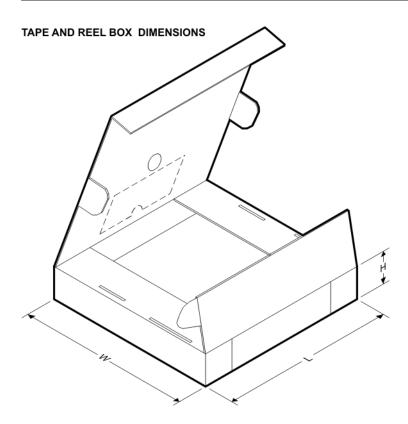


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3800G27DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3800G27DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801-01DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3801-01DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801E18DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801E18DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3801I50DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801J25DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801K33DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801K33DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3801L30DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3801T50DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3801T50DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3802K33DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3802K33DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3802L30DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
TPS3802L30DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3



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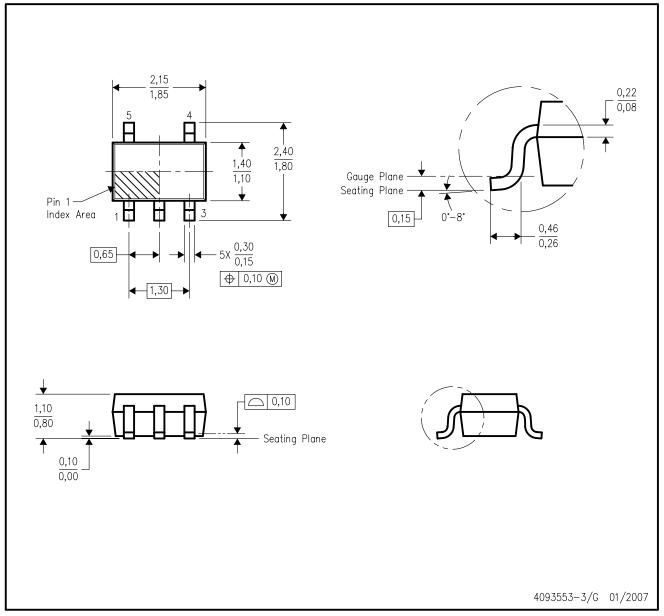


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3800G27DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3800G27DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801-01DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3801-01DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801E18DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801E18DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3801I50DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801J25DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801K33DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801K33DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3801L30DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3801T50DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3801T50DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3802K33DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3802K33DCKR	SC70	DCK	5	3000	202.0	201.0	28.0
TPS3802L30DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
TPS3802L30DCKR	SC70	DCK	5	3000	202.0	201.0	28.0

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



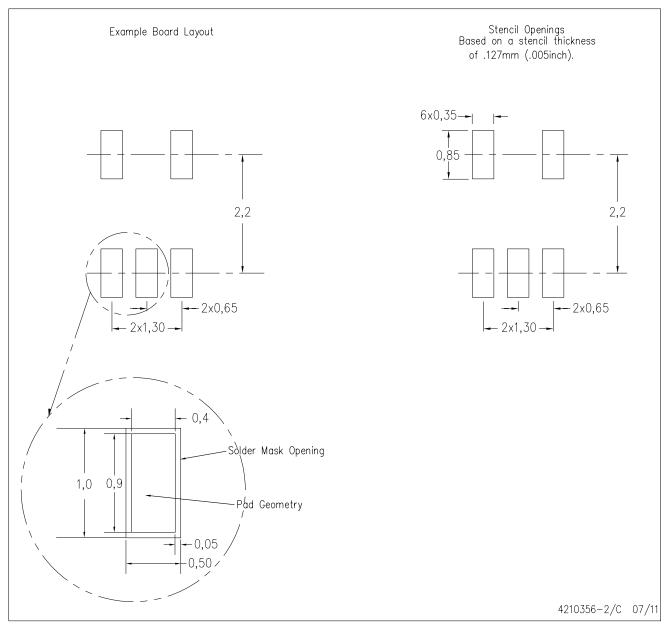
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AA.



DCK (R-PDSO-G5)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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